



Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at
www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

MM74HCT240 • MM74HCT244

Inverting Octal 3-STATE Buffer • Octal 3-STATE Buffer

General Description

The MM74HCT240 and MM74HCT244 3-STATE buffers utilize advanced silicon-gate CMOS technology and are general purpose high speed inverting and non-inverting buffers. They possess high drive current outputs which enable high speed operation even when driving large bus capacitances. These circuits achieve speeds comparable to low power Schottky devices, while retaining the low power consumption of CMOS. All three devices are TTL input compatible and have a fanout of 15 LS-TTL equivalent inputs.

MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices. These parts are also plug-in replacements for LS-TTL devices and can be used to reduce power consumption in existing designs.

The MM74HCT240 is an inverting buffer and the MM74HCT244 is a non-inverting buffer. Each device has two active low enables (1G and 2G), and each enable independently controls 4 buffers.

All inputs are protected from damage due to static discharge by diodes to V_{CC} and Ground.

Features

- TTL input compatible
- Typical propagation delay: 14 ns
- 3-STATE outputs for connection to system buses
- Low quiescent current: 80 μ A
- High output drive current: 6 mA (min)

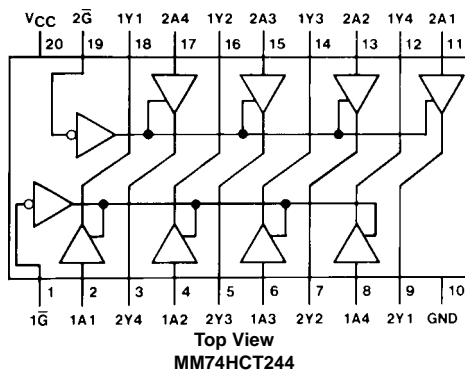
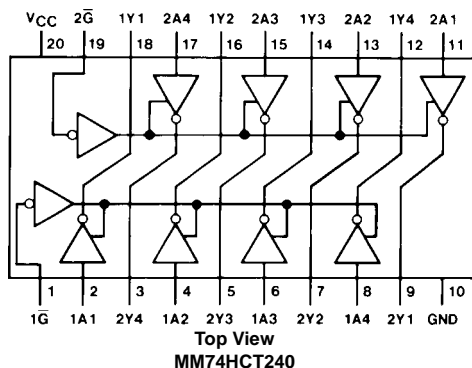
Ordering Code:

Order Number	Package Number	Package Description
MM74HCT240WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HCT240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HCT240MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HCT240N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
MM74HCT244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HCT244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HCT244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HCT244N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagrams

Pin Assignments for DIP, SOIC, SOP and TSSOP



Truth Tables

MM74HCT240

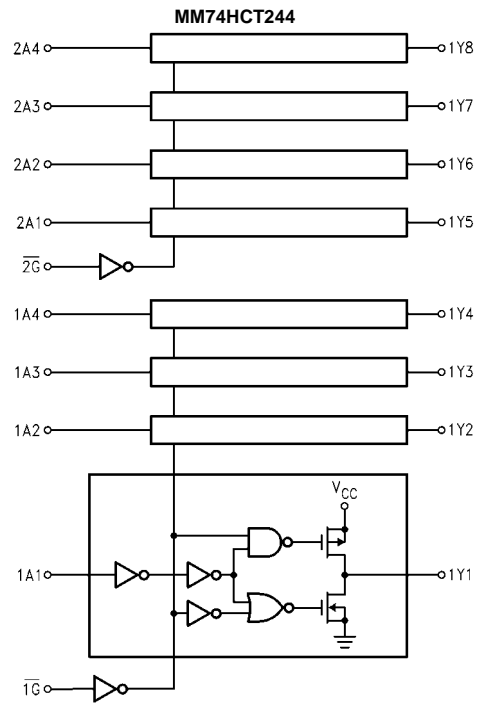
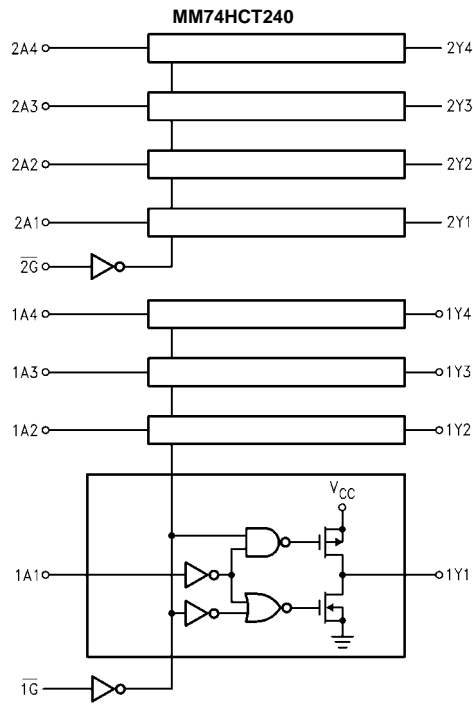
1 \bar{G}	1A	1Y	2 \bar{G}	2A	2Y
L	L	H	L	L	H
L	H	L	L	H	L
H	L	Z	H	L	Z
H	H	Z	H	H	Z

H = HIGH Level L = LOW Level Z = High Impedance

MM74HCT244

1 \bar{G}	1A	1Y	2 \bar{G}	2A	2Y
L	L	L	L	L	L
L	H	H	L	H	H
H	L	Z	H	L	Z
H	H	Z	H	H	Z

Logic Diagrams



Absolute Maximum Ratings ^(Note 1)		Recommended Operating Conditions	
^(Note 2)		Min	Max
Supply Voltage (V_{CC})	-0.5 to +7.0V	4.5	5.5
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$	0	V_{CC}
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$		
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA		
DC Output Current, per pin (I_{OUT})	± 35 mA		
DC V_{CC} or GND Current, per pin (I_{CC})	± 70 mA		
Storage Temperature Range (T_{STG})	-65°C to +150°C		
Power Dissipation (P_D)			500 ns
^(Note 3)	600 mW		
S.O. Package only	500 mW		
Lead Temperature (T_L)			
(Soldering 10 seconds)	260°C		

DC Electrical Characteristics		$T_A = 25^\circ C$		$T_A = -40$ to $85^\circ C$	$T_A = -55^\circ$ to $125^\circ C$	Units
Symbol	Parameter	Conditions	Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage		2.0	2.0	2.0	V
V_{IL}	Maximum LOW Level Input Voltage		0.8	0.8	0.8	V
V_{OH}	Minimum HIGH Level Output Voltage	$V_{IN-EE} = V_{IH}$ or V_{IL}	V_{CC}	$V_{CC}-0.1$	$V_{CC}-0.1$	$V_{CC}-0.1$
		$I_{OUT} = 20 \mu A$	4.2	3.98	3.84	3.7
		$I_{OUT} = 6.0$ mA, $V_{CC} = 4.5V$	5.2	4.98	4.84	4.7
V_{OL}	Maximum LOW Level Voltage	$V_{IN} = V_{IH}$ or V_{IL}	0	0.1	0.1	0.1
		$I_{OUT} = 20 \mu A$	0.2	0.26	0.33	0.4
		$I_{OUT} = 6.0$ mA, $V_{CC} = 4.5V$	0.2	0.26	0.33	0.4
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND, V_{IH} or V_{IL}		± 0.05	± 0.5	± 1.0
I_{OZ}	Maximum 3-STATE Output Leakage Current	$V_{OUT} = V_{CC}$ or GND $\bar{G} = V_{IH}$ $G = V_{IL}$		± 0.25	± 2.5	± 10
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$		4.0	40	160
		$V_{IN} = 2.4V$ or $0.5V$ (Note 4)	0.6	1.0	1.3	1.5

Note 4: Measured per input. All other inputs at V_{CC} or GND.

AC Electrical Characteristics

MM74HCT240, MM74HCT244 $V_{CC} = 5.0V$, $t_r = t_f = 6$ ns, $T_A = 25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Conditions	Typ	Guaranteed Limits	Units
t_{PHL} , t_{PLH}	Maximum Output Propagation Delay	$C_L = 45$ pF	14	18	ns
t_{PZL} , t_{PZH}	Maximum Output Enable Time	$C_L = 45$ pF $R_L = 1$ k Ω	20	30	ns
t_{PLZ} , t_{PHZ}	Maximum Output Disable Time	$C_L = 5$ pF $R_L = 1$ k Ω	16	25	ns

AC Electrical Characteristics

MM74HCT240, MM74HCT244 $V_{CC} = 5.0V \pm 10\%$, $t_r = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	$T_A = 25^\circ C$			Units		
			Typ	Guaranteed Limits				
t_{PHL} , t_{PLH}	Maximum Output Propagation Delay	$C_L = 50$ pF	14	20	25	30	ns	
		$C_L = 150$ pF	20	28	35	42	ns	
t_{PZH} , t_{PZL}	Maximum Output Enable Time	$R_L = 1$ k Ω	$C_L = 50$ pF	21	30	38	45	ns
			$C_L = 150$ pF	26	42	53	63	ns
t_{PHZ} , t_{PLZ}	Maximum Output Disable Time	$R_L = 1$ k Ω $C_L = 50$ pF	16	25	32	38	ns	
t_{THL} , t_{TLH}	Maximum Output Rise and Fall Time	$C_L = 50$ pF	6	12	15	18	ns	
C_{IN}	Maximum Input Capacitance		10	15	15	15	pF	
C_{OUT}	Maximum Output Capacitance		15	20	20	20	pF	
C_{PD}	Power Dissipation Capacitance (Note 5)	(per buffer) $\bar{G} = V_{CC}$, $G = GND$	5				pF	
		$\bar{G} = GND$, $G = V_{CC}$	90				pF	

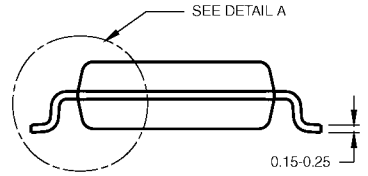
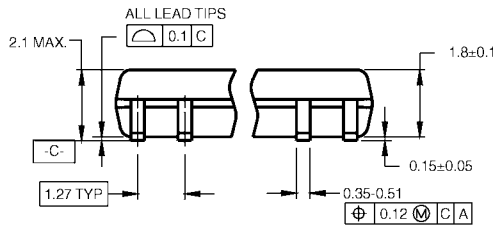
Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters) unless otherwise noted



**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B**

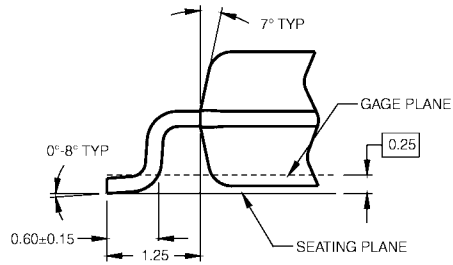
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

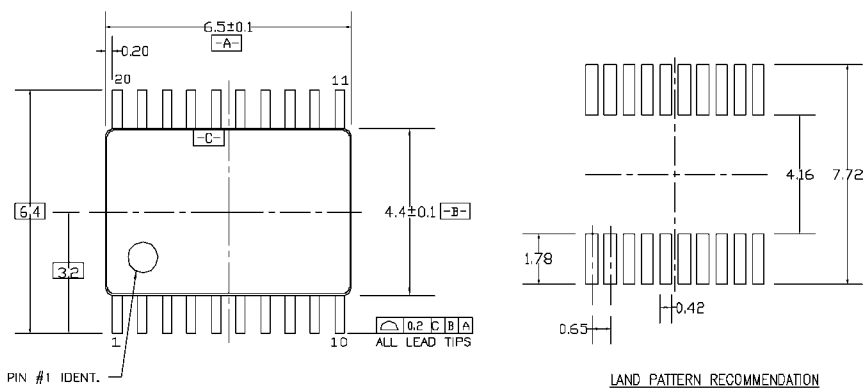
M20DRevB1



DETAIL A

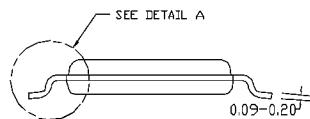
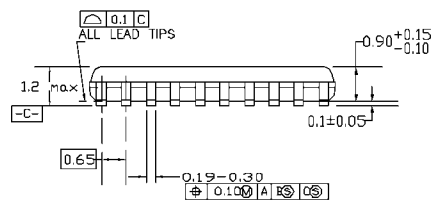
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
 Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

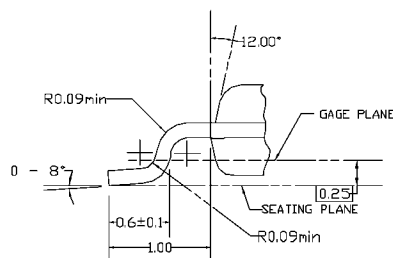


PIN #1 IDENT.

LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

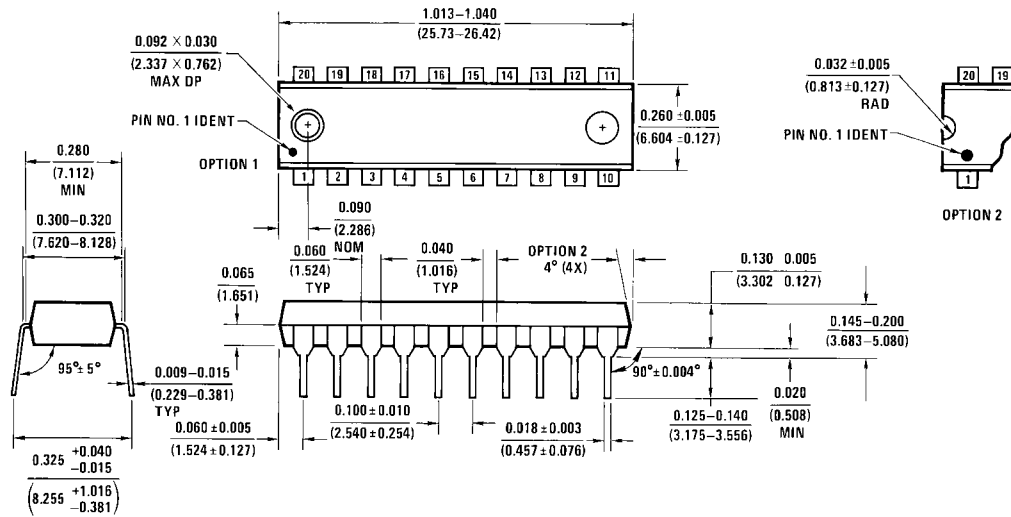
NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N20A

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>
For additional information, please contact your local
Sales Representative